

ABSTRACT OF THE DISCLOSURE

[40] The present invention relates to a method of forming a conductive layer and an electroplating device, and in particular, to a method of forming a conductive layer that provides an electrically-conductive layer having both characteristics of increased adhesiveness to an electroplated body and increased uniformity. The electroplating apparatus and method can produce supersonic waves for electroplating. Thus, the electroplating device can include a wave generator. The electroplating device can further include a plating bath filled with an electrolyte solution that can propagate super sonic waves, a power supply, a plated body connected electrically to a first terminal of the power supply, and a plating body connected electrically to a second terminal of the power supply where the plating body provides ions the same as dissolved in the electrolyte solution to maintain a desired concentration of dissolved ions.